Product data sheet

1. General description

Silicon Carbide Schottky diode in a TO252 (DPAK) plastic package, designed for high frequency switched-mode power supplies.



2. Features and benefits

- · Highly stable switching performance
- High forward surge capability I_{FSM}
- Extremely fast reverse recovery time
- Superior in efficiency to Silicon Diode alternatives
- Reduced losses in associated MOSFET
- Reduced EMI
- Reduced cooling requirements
- RoHS compliant
- High junction operating temperature capability (T_{i(max)} = 175 °C)

3. Applications

- Power factor correction
- Telecom / Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED / OLED TV
- Motor Drives

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes		Values		Unit
Absolute	maximum rating						
V_{RRM}	repetitive peak reverse voltage				1200		V
l _F	continuous forward current	T _{mb} ≤ 163 °C, DC; <u>Fig. 2</u>			2		А
T _j	junction temperature				175		°C
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static ch	aracteristics						
V _F	forward voltage	I _F = 2 A; T _j = 25 °C; <u>Fig. 5</u>		-	1.42	1.60	V
		I _F = 2 A; T _j = 150 °C; <u>Fig. 5</u>		-	1.90	2.30	V
Dynamic	characteristics						
Q _r	recovered charge	$I_F = 2 \text{ A}; dI_F/dt = 500 \text{ A/}\mu\text{s}; V_R = 400 \text{ V};$ $T_j = 25 \text{ °C}; Fig. 7$		-	4	-	nC

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	n.c.	not connected		к I/I л
2	K	cathode [1]		K A 001aaa020
3	Α	anode		
mb	К	mounting base; connected to cathode		

^[1] It is not possible to connect to pin 2 of the TO252 package.

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WNSC2D021200D	TO252	WNSC2D021200D6J	Reel	2500	TO252NS	14-Nov-2016

7. Marking

Table 4. Marking codes

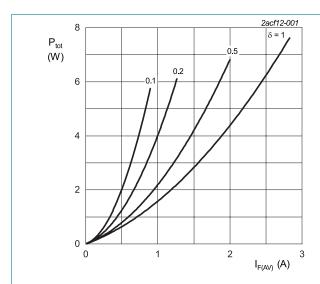
Type number	Marking codes
WNSC2D021200D	WNSC2D 021200D

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
V_{RRM}	repetitive peak reverse voltage			1200	V
V_{RWM}	crest working reverse voltage			1200	V
V_R	reverse voltage	DC		1200	V
I _F	continuous forward	T _{mb} ≤ 163 °C, DC; <u>Fig. 2</u>		2	Α
	current	T _{mb} ≤ 125 °C, DC; <u>Fig. 2</u>		4	Α
		T _{mb} ≤ 25 °C, DC; <u>Fig. 2</u>		8	Α
I _{FRM}	repetitive peak forward current	δ = 0.5; t_p = 25 μ s; T_{mb} = 125 °C; square-wave pulse		6	A
I _{FSM}	non-repetitive peak	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse		26	Α
	forward current	t_p = 10 μ s; $T_{j(init)}$ = 25 °C; square-wave pulse		200	Α
l ² t	I ² t for fusing	sine-wave pulse; $T_{j(init)}$ = 25 °C; t_p = 10 ms		3.38	A ² s
T _{stg}	storage temperature			-55 to 175	°C
T _j	junction temperature			-55 to 175	°C



 $\begin{aligned} I_{F(AV)} &= I_{F(RMS)} \times \sqrt{\delta} \\ V_o &= 0.972 \text{ V; R}_s = 0.6094 \text{ }\Omega \end{aligned}$

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values

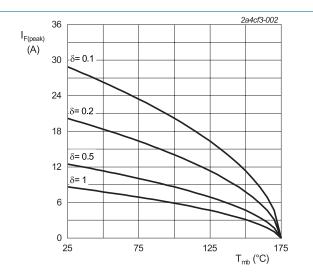


Fig. 2. Current derating as a function of mounting base temperature

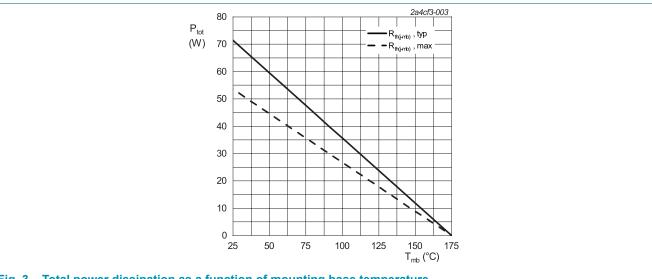


Fig. 3. Total power dissipation as a function of mounting base temperature

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
R _{th(j-mb)}	thermal resistance from junction to mounting base	with heatsink compound; Fig. 4		-	2.1	2.8	K/W
R _{th(j-a)}	thermal resistance from junction to ambient free air	in free air		-	60	-	K/W

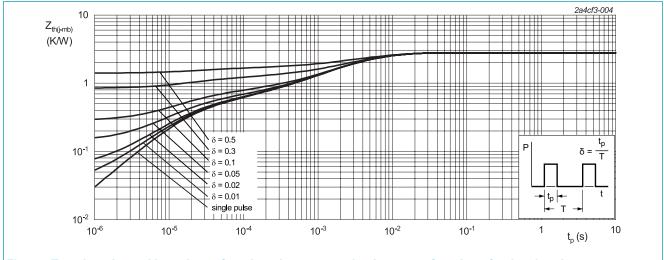
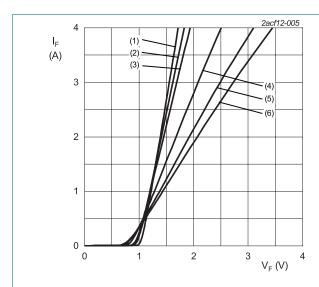


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

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Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static cha	racteristics						
V_{F}	forward current	I _F = 2 A; T _j = 25 °C; <u>Fig. 5</u>		-	1.42	1.60	V
		I _F = 2 A; T _j = 150 °C; <u>Fig. 5</u>		-	1.90	2.30	V
		I _F = 2 A; T _j = 175 °C; <u>Fig. 5</u>		-	2.00	2.50	V
I _R	reverse current	V _R = 1200 V; T _j = 25 °C; <u>Fig. 6</u>		-	0.5	10	μΑ
		V _R = 1200 V; T _j = 175 °C; <u>Fig. 6</u>		-	25	-	μΑ
Dynamic	characteristics						
Q_{r}	recovered charge	$I_F = 2 \text{ A}$; $V_R = 400 \text{ V}$; $dI_F/dt = 500 \text{ A/}\mu\text{s}$; $T_j = 25 \text{ °C}$; Fig. 7		-	4	-	nC
C _d	diode capacitance	f = 1 MHz; V _R = 1 V; T _j = 25 °C		-	95	-	pF
		f = 1 MHz; V _R = 400 V; T _j = 25 °C		-	10	-	pF
		f = 1 MHz; V _R = 800 V; T _j = 25 °C		-	8	-	pF
E _{as}	non-repetitive avalanche energy	$I_R = 2 \text{ A}$; L = 10 mH; $T_{j(init)} = 25 \text{ °C}$		18	-	-	mJ



 $V_0 = 0.972 \text{ V}; R_s = 0.6094 \Omega$

(1) T_i = -55 °C; typical values

(2) T_i = 0 °C; typical values

(3) T_i = 25 °C; typical values

(4) T_j = 100 °C; typical values (5) T_j = 150 °C; typical values (6) T_j = 175 °C; typical values

Fig. 5. Forward current as a function of forward voltage; typical values

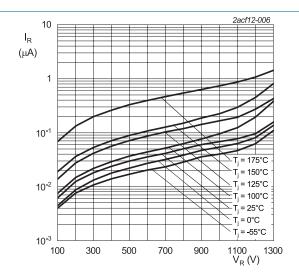
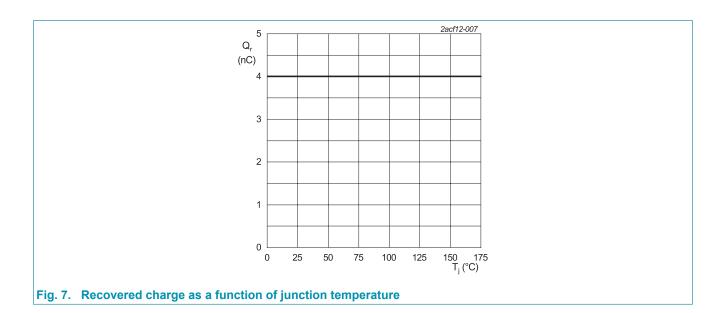
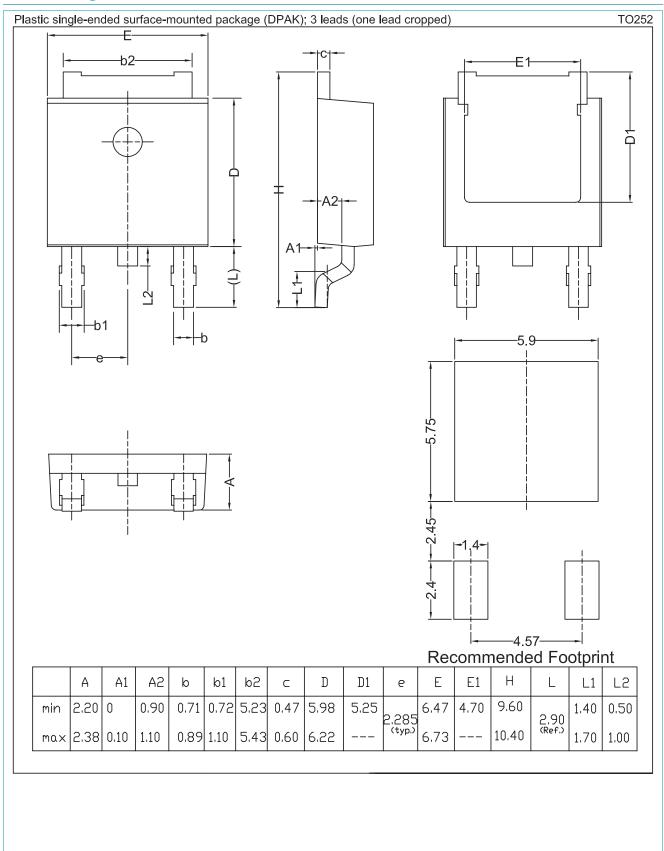


Fig. 6. Reverse leakage current as a function of reverse voltage; typical value



11. Package outline



12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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